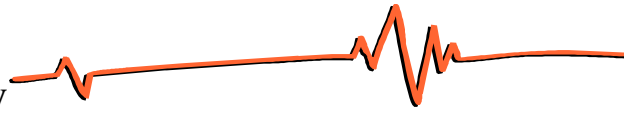


Electronics Recovery

Service, Inc.



Pricing and Quote worksheet (updated 7/2008)

Electronics Recovery Service, Inc. provides superior rework service to all our customers. Each rework or repair is priced on an individual basis with a typical BGA removal and replacement starting at \$75.00. All orders include x-ray and endoscopic inspection.

Lead Time: Our standard lead time is 5 business days after receipt of all documentation and materials.

Payment / Terms: ERS accepts Visa, Mastercard and company check. Net 30 terms are available to qualified customers.

Shipping: All orders are shipped F.O.B. origin. Preferred carrier is UPS unless otherwise specified. Customers may provide their shippers account number for billing. A pass-through shipping charge may be added to invoice when customer account information is not supplied. Additional protective packaging material charges may also apply if not provided.

Information requested to provide accurate quote:

(The more information provided, the more accurate the quote)

- Why is the rework to be performed? Engineering Change, Mfg. Defect, etc.
- Has a previous attempt been made to repair?
- Quantity and delivery requirements. Standard lead-time is 5 business days.
- What type of component? BGA, uBGA, QFN... mechanical data sheet requested.
- What alloy of solder, solder sphere? Sn/Pb (tin/lead), Rohs (Lead Free, SAC alloy?)
- Dimension of PCB/substrate, thickness, and if a lead free process the manufacturer and type of substrate material. (necessary to determine glass transition temperature rating, Tg, etc.)
- Are vias and/or plated feed-through holes beneath component solder mask tented?
- Are there any clearance issues around the component or on the secondary side that would prevent even reflow heating?
- Is there conformal coating, underfill, heatsink or other factors that thermally or mechanically hinder component removal?
- If not delivered in factory sealed packaging or if reballing is requested an additional 24 hour moisture bake-out is required to prevent internal damage to components during reflow cycle.